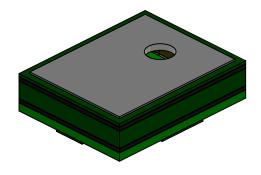
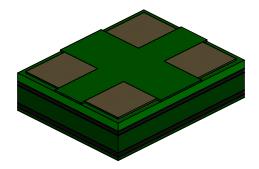


"Mini" SiSonic™ Microphone Specification - Halogen Free





Knowles Acoustics 1151 Maplewood Drive Itasca, IL 60143





#### 1. DESCRIPTION AND APPLICATION

1.1 DESCRIPTION: "Mini" Surface Mount Silicon Microphone

1.2 APPLICATION: Hand held telecomunication devices.

#### 2. PART MARKING

Identification Number Convention

S 1 2 3

4 5 6 7

S: Manufacturing Location "S" - Knowles Electronics Suzhou Suzhou, China

> "No Alpha Character" - Knowles Electronics Itasca, IL USA

"E" - Engineering Samples

Digits 1-7: Job Identification Number

#### 3. TEMPERATURE RANGE

3.1 Operating Temperature Range: -40°C to +100°C

3.2 Storage Temperature Range: -40°C to +100°C

#### 4. ABSOLUTE MAXIMUM RATINGS

Parameter	Absolute Maximum Rating	Unit
Supply Voltage, V <sub>DD</sub> to Ground	-0.5, +5.0	٧
OUT to Ground	-0.3, V <sub>DD</sub> +0.3	V
Input Current to Any Pin	±5	mΑ

Stresses at these Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only. The device may not function when operated at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications". Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.



Sheet 2 of 10



### 5. ACOUSTIC & ELECTRICAL SPECIFICATIONS

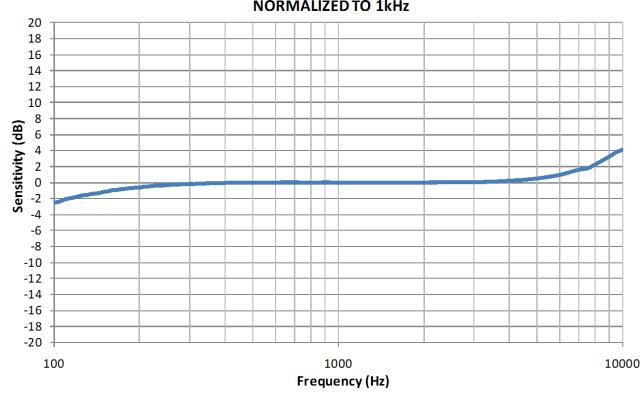
TEST CONDITIONS: 23  $\pm$  2°C, 60-70% R.H.,  $V_{DD}$  (min)  $\leq V_{DD} \leq V_{DD}$  (max), no load, unless otherwise specified

Deveno	Cymala al	mbol Condition		Limits		11	
Parameter	Symbol	Condition	Min.	Nom.	Max.	Unit	
Supply Voltage <sup>1</sup>	V <sub>DD</sub>		1.5		3.6	V	
Current Consumption 1	IDD				250	μA	
Directivity				Omni-di	rectional		
Sensitivity <sup>1</sup>	S	94 dB SPL @ 1kHz	-45	-42	-39	dBV/Pa	
Signal to Noise Ratio	SNR	94 dB SPL @ 1kHz, A-weighted		59		dB(A)	
Output Impedance		@ 1kHz			100	Ω	
Total Harmonic	THUTN	100 dB SPL @ 1kHz			1	%	
Distortion + Noise	וווטדוו	115 dB SPL @ 1kHz			10	%	
Polarity		Increasing sound pressure	Decr	easing o	utput vo	ltage	

<sup>100%</sup> tested

#### 6. FREQUENCY RESPONSE CURVE

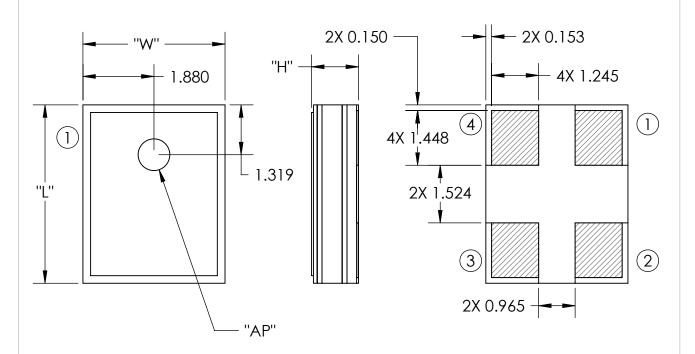
# TYPICAL FREE FIELD RESPONSE NORMALIZED TO 1kHz







#### 7. MECHANICAL SPECIFICATIONS



ITEA A	DIMENICION	TOLEDANIOE	LINITE
ITEM	DIMENSION	TOLERANCE	UNITS
LENGTH (L)	4.720	±0.100	mm
WIDTH (W)	3.760	±0.100	mm
HEIGHT (H)	1.250	±0.100	mm
ACOUSTIC	Ø0.838	±0.100	mm
PORT (AP)	Ø0.030	±0.100	mm

	PIN OUTPUT
PIN #	FUNCTION
1	OUTPUT
2	GROUND
3	GROUND
4	POWER (VDD)

#### Note:

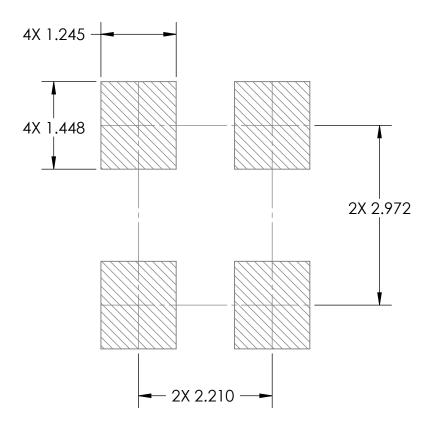
Dimensions are in milimeters unless otherwise specified.

Tolerance  $\pm 0.15$ mm unless otherwise specified.





#### 8. RECOMMENDED CUSTOMER LAND PATTERN



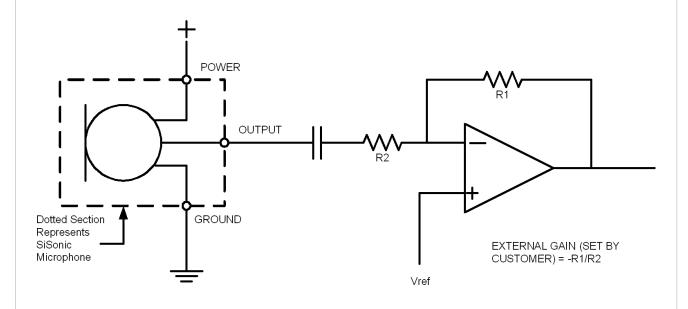
### 9. RECOMMENDED SOLDER STENCIL PATTERN

N/A





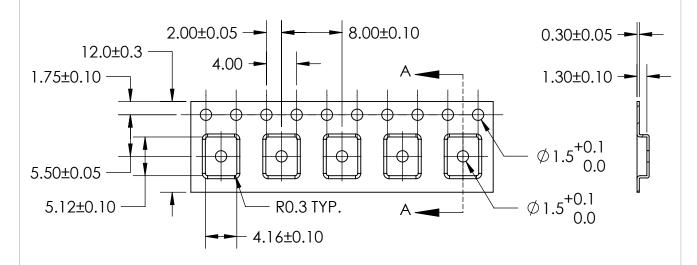
### 10. RECOMMENDED INTERFACE CIRCUIT

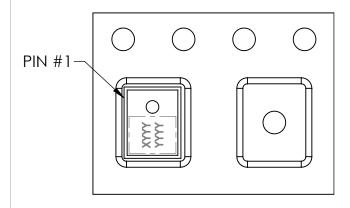






#### 11. PACKAGING DETAIL





COMPONENT **ORIENTATION** 

MODEL NUMBER	SUFFIX	REEL DIAMETER	QUANTITY PER REEL
CDMO404HDC DD /D-	-2	7''	1,200
SPM0404HD5-PB (Re	V A) -6	13"	4,800

TAPE & REEL	PER EIA-481
II ABEI	LABEL APPLIED TO EXTERNAL PACKAGE & DIRECT TO REEL.

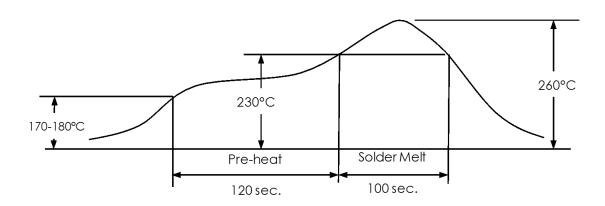
Note:

Dimensions are in milimeters unless otherwise specified.





#### 12. SOLDER FLOW PROFILE



Stage	Temperature Profile	Time (maximum)
Pre-heat	170 ~ 180°C	120 sec.
Solder Melt	Above 230°C	100 sec.
Peak	260°C maximum	30 sec.

#### 13. ADDITIONAL NOTES

- Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.
- MSL (moisture sensitivity level) Class 2a.
- Do not pull a vacuum over port hole of the microphone. Pulling a vacuum over the
- port hole can damage the device.

  Do not board wash after the reflow process. Board washing and cleaning agents can damage the device. Do not expose to ultrasonic processing or cleaning.
- Do not brush board after the reflow process. Brushing the board with/without (E) solvents can damage the device.
- Do not insert any object in port hole of device at any time as this can damage the (F) device.
- Number of reflow Recommend no more than 3 cycles. (G)



Knowles Acoustics, a division of Knowles Electronics, LLC.

Release Level: ACTIVE Sheet 8 of 10



### 14. RELIABILITY SPECIFICATIONS

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

Test	Description	
Thermal Shock	100 cycles of air-air thermal shock from -40°C to +125°C with 15 minute soaks. (IEC 68-2-4)	
High Temperature Storage	+105°C environment for 1,000 hours. (IEC 68-2-2 Test Ba)	
Low Temperature Storage	-40°C environment for 1,000 hours. (IEC 68-2-2 Test Aa)	
High Temperature Bias	+105°C environment while under bias for 1,000 hours. (IEC 68-2-2 Test Ba)	
Low Temperature Bias	-40°C environment while under bias for 1,000 hours. (IEC 68-2-2 Test Aa)	
Temperature / Humidity Bias	+85°C/85% R.H. environment while under bias for 1,000 hours. (JESD22-A101A-B)	
Vibration	4 cycles lasting 12 minutes from 20 TO 2,000 Hz in X, Y and Z direction with peak acceleration of 20g. (MIL 883E, Method 2007.2, A)	
Electrostatic Discharge	3 discharges at +/-8kV direct contact to lid when unit is grounded (IEC 61000-4-2) and 3 discharges at +/-2kV direct contact to I/O pins. (MIL 883E, Method 3015.7)	
Reflow	5 reflow cycles with peak temperature of +260°C.	
Mechanical Shock	3 pulses of 10,000g in the X, Y and Z direction. (IEC 68-2-27, Test Ea) $$	





#### 15. SPECIFICATION REVISIONS

Revision	Detailed Specification Changes	Date
Α	INITIAL DRAWING	1/17/11

The information contained in this literature is based on our experience to date and is believed to be reliable and it is subject to change without notice. It is intended as a guide for use by persons having technical skill at their own discretion and risk. We do not guarantee favorable results or assume any liability in connection with its use. Dimensions contained herein are for reference purposes only. For specific dimensional requirements consult factory. This publication is not to be taken as a license to operate under, or recommendation to infringe any existing patents. This supersedes and voids all previous literature.

